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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	76
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	36K x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 3.6V
Data Converters	A/D 24x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1519jbd100e

- Single power supply 2.4 V to 3.6 V.
- Temperature range −40 °C to +105 °C.
- Available as LQFP100, LQFP64, and LQFP48 packages.

3. Applications

- Motor control
- Motion drives
- Digital power supplies
- Industrial and medical
- Solar inverters
- Home appliances
- Building and factory automation

4. Ordering information

Table 1. Ordering information

Type number	Package		
	Name	Description	Version
LPC1549JBD100	LQFP100	plastic low profile quad flat package; 100 leads; body 14 × 14 × 1.4 mm	SOT407-1
LPC1549JBD64	LQFP64	plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC1549JBD48	LQFP48	plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1548JBD100	LQFP100	plastic low profile quad flat package; 100 leads; body 14 × 14 × 1.4 mm	SOT407-1
LPC1548JBD64	LQFP64	plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC1547JBD64	LQFP64	plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC1547JBD48	LQFP48	plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC1519JBD100	LQFP100	plastic low profile quad flat package; 100 leads; body 14 × 14 × 1.4 mm	SOT407-1
LPC1519JBD64	LQFP64	plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC1518JBD100	LQFP100	plastic low profile quad flat package; 100 leads; body 14 × 14 × 1.4 mm	SOT407-1
LPC1518JBD64	LQFP64	plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC1517JBD64	LQFP64	plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC1517JBD48	LQFP48	plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2

Table 3. Pin description with fixed-pin functions

Symbol	LQFP48	LQFP64	LQFP100		Reset state[1]	Type	Description
PIO0_27/ACMP_I1	46	62	97	[2]	I; PU	IO	**PIO0_27 —** General purpose port 0 input/output 27.
						A	**ACMP_I1 —** Analog comparator common input 1.
PIO0_28/ACMP1_I3	47	63	98	[2]	I; PU	IO	**PIO0_28 —** General purpose port 0 input/output 28.
						A	**ACMP1_I3 —** Analog comparator 1 input 3.
PIO0_29/ACMP2_I3/ SCT2_OUT4	48	64	100	[2]	I; PU	IO	**PIO0_29 —** General purpose port 0 input/output 29.
						A	**ACMP2_I3 —** Analog comparator 2 input 3.
						O	**SCT2_OUT4 —** SCTimer2/PWM output 4.
PIO0_30/ADC0_11	-	1	1	[2]	I; PU	IO	**PIO0_30 —** General purpose port 0 input/output 30.
						A	**ADC0_11 —** ADC0 input 11.
PIO0_31/ADC0_9	-	3	3	[2]	I; PU	IO	**PIO0_31 —** General purpose port 0 input/output 31. On the LQFP64 package, this pin is assigned to CAN0_TD in ISP C_CAN mode.
						A	**ADC0_9 —** ADC0 input 9.
PIO1_0/ADC0_8	-	4	5	[2]	I; PU	IO	**PIO1_0 —** General purpose port 1 input/output 0.
						A	**ADC0_8 —** ADC0 input 8.
PIO1_1/ADC1_0	-	15	23	[2]	I; PU	IO	**PIO1_1 —** General purpose port 1 input/output 1.
						A	**ADC1_0 —** ADC1 input 0.
PIO1_2/ADC1_4	-	25	36	[2]	I; PU	IO	**PIO1_2 —** General purpose port 1 input/output 2.
						A	**ADC1_4 —** ADC1 input 4.
PIO1_3/ADC1_5	-	28	41	[2]	I; PU	IO	**PIO1_3 —** General purpose port 1 input/output 3.
						A	**ADC1_5 —** ADC1 input 5.
PIO1_4/ADC1_10	-	33	51	[2]	I; PU	IO	**PIO1_4 —** General purpose port 1 input/output 4.
						A	**ADC1_10 —** ADC1 input 10.
PIO1_5/ADC1_11	-	34	52	[2]	I; PU	IO	**PIO1_5 —** General purpose port 1 input/output 5.
						A	**ADC1_11 —** ADC1 input 11.
PIO1_6/ACMP_I2	-	46	73	[2]	I; PU	IO	**PIO1_6 —** General purpose port 1 input/output 6.
						A	**ACMP_I2 —** Analog comparator common input 2.
PIO1_7/ACMP3_I4	-	51	81	[2]	I; PU	IO	**PIO1_7 —** General purpose port 1 input/output 7.
						A	**ACMP3_I4 —** Analog comparator 3 input 4.
PIO1_8/ACMP3_I3/ SCT3_OUT4	-	53	84	[2]	I; PU	IO	**PIO1_8 —** General purpose port 1 input/output 8.
						A	**ACMP3_I3 —** Analog comparator 3 input 3.
						O	**SCT3_OUT4 —** SCTimer3/PWM output 4.
PIO1_9/ACMP2_I4	-	54	85	[2]	I; PU	IO	**PIO1_9 —** General purpose port 1 input/output 9. On the LQFP64 package, this is the ISP_0 boot pin.
						A	**ACMP2_I4 —** Analog comparator 2 input 4.
PIO1_10/ACMP1_I4	-	59	91	[2]	I; PU	IO	**PIO1_10 —** General purpose port 1 input/output 10.
						A	**ACMP1_I4 —** Analog comparator 1 input 4.
PIO1_11	-	38	58	[5]	I; PU	IO	**PIO1_11 —** General purpose port 1 input/output 11. On the LQFP64 package, this is the ISP_1 boot pin.

8.9 Nested Vectored Interrupt controller (NVIC)

The Nested Vectored Interrupt Controller (NVIC) is part of the Cortex-M3. The tight coupling to the CPU allows for low interrupt latency and efficient processing of late arriving interrupts.

8.9.1 Features

- Nested Vectored Interrupt Controller that is an integral part of the ARM Cortex-M3.
- Tightly coupled interrupt controller provides low interrupt latency.
- Controls system exceptions and peripheral interrupts.
- The NVIC supports 47 vectored interrupts.
- Eight programmable interrupt priority levels with hardware priority level masking.
- Software interrupt generation using the ARM exceptions SVCall and PendSV.
- Support for NMI.
- ARM Cortex-M3 Vector table offset register VTOR implemented.

8.9.2 Interrupt sources

Typically, each peripheral device has one interrupt line connected to the NVIC but can have several interrupt flags. Individual interrupt flags can also represent more than one interrupt source.

8.10 IOCON block

The IOCON block configures the electrical properties of the pins such as pull-up and pull-down resistors, hysteresis, open-drain modes and input filters.

Remark: The pin function and whether the pin operates in digital or analog mode are entirely under the control of the switch matrix.

Enabling an analog function through the switch matrix disables the digital pad. However, the internal pull-up and pull-down resistors as well as the pin hysteresis must be disabled to obtain an accurate reading of the analog input.

8.10.1 Features

- Programmable pull-up, pull-down, or repeater mode.
- All pins (except PIO0_22 and PIO0_23) are pulled up to 3.3 V (V_{DD} = 3.3 V) if their pull-up resistor is enabled.
- Programmable pseudo open-drain mode.
- Programmable (on/off) 10 ns glitch filter on 36 pins (PIO0_0 to PIO0_17, PIO0_25 to PIO0_31, PIO1_0 to PIO1_10). The glitch filter is turned on by default.
- Programmable hysteresis.
- Programmable input inverter.
- Digital filter with programmable filter constant on all pins.

8.10.2 Standard I/O pad configuration

Figure 11 shows the possible pin modes for standard I/O pins with analog input function:

8.24.1 Features

- 12-bit successive approximation analog-to-digital converter.
- 12-bit conversion rate of 2 MHz.
- Input multiplexing among 12 pins and up to 4 internal sources.
- Internal sources are the temperature sensor voltage, internal reference voltage, core voltage regulator output, and VDDA/2.
- Two configurable conversion sequences with independent triggers.
- Optional automatic high/low threshold comparison and zero-crossing detection.
- Power-down mode and low-power operating mode.
- Measurement range VREFN to VREFP (typically 3 V; not to exceed VDDA voltage level).
- Burst conversion mode for single or multiple inputs.
- Synchronous or asynchronous operation. Asynchronous operation maximizes flexibility in choosing the ADC clock frequency, Synchronous mode minimizes trigger latency and can eliminate uncertainty and jitter in response to a trigger.

8.25 Digital-to-Analog Converter (DAC)

The DAC supports a resolution of 12 bits. Conversions can be triggered by an external pin input or an internal timer.

The DAC includes an optional automatic hardware shut-off feature which forces the DAC output voltage to zero while a HIGH level on the external DAC_SHUTOFF pin is detected.

8.25.1 Features

- 12-bit digital-to-analog converter.
- Supports DMA.
- Internal timer or pin external trigger for staged, jitter-free DAC conversion sequencing.
- Automatic hardware shut-off triggered by an external pin.

8.26 Analog comparator (ACMP)

The LPC15xx include four analog comparators with seven selectable inputs each for each positive or negative input channel. Two analog inputs are common to all four comparators. Internal voltage inputs include a voltage ladder reference with selectable voltage supply source, the temperature sensor or the internal voltage reference.

The analog inputs to the comparators are fixed-pin functions and must be enabled through the switch matrix.

The outputs of each analog comparator are internally connected to the ADC trigger inputs and to the SCT inputs, so that the result of a voltage comparison can trigger a timer operation or an analog-to-digital conversion.

8.31 Repetitive Interrupt (RI) timer

The repetitive interrupt timer provides a free-running 48-bit counter which is compared to a selectable value, generating an interrupt when a match occurs. Any bits of the timer/compare can be masked such that they do not contribute to the match detection. The repetitive interrupt timer can be used to create an interrupt that repeats at predetermined intervals.

8.31.1 Features

- 48-bit counter running from the main clock. Counter can be free-running or can be reset when an RIT interrupt is generated.
- 48-bit compare value.
- 48-bit compare mask. An interrupt is generated when the counter value equals the compare value, after masking. This allows for combinations not possible with a simple compare.

8.32 System tick timer

The ARM Cortex-M3 includes a system tick timer (SYSTICK) that is intended to generate a dedicated SYSTICK exception at a fixed time interval (typically 10 ms).

8.33 Real-Time Clock (RTC)

The RTC resides in a separate, always-on voltage domain with battery back-up. The RTC uses an independent 32 kHz oscillator, also located in the always-on voltage domain.

8.33.1 Features

- 32-bit, 1 Hz RTC counter and associated match register for alarm generation.
- Separate 16-bit high-resolution/wake-up timer clocked at 1 kHz for 1 ms resolution with a more that one minute maximum time-out period.
- RTC alarm and high-resolution/wake-up timer time-out each generate independent interrupt requests. Either time-out can wake up the part from any of the low power modes, including Deep power-down.

8.41 System control

8.41.1 Reset

Reset has four sources on the LPC15xx: the $\overline{\text{RESET}}$ pin, the Watchdog reset, power-on reset (POR), and the BrownOut Detection (BOD) circuit. The $\overline{\text{RESET}}$ pin is a Schmitt trigger input pin. Assertion of chip reset by any source, once the operating voltage attains a usable level, starts the IRC and initializes the flash controller.

When the internal Reset is removed, the processor begins executing at address 0, which is initially the Reset vector mapped from the boot block. At that point, all of the processor and peripheral registers have been initialized to predetermined values.

In Deep power-down mode, an external pull-up resistor is required on the $\overline{\text{RESET}}$ pin.

The $\overline{\text{RESET}}$ pin is operational in active, sleep, deep-sleep, and power-down modes if the $\overline{\text{RESET}}$ function is selected through the switch matrix for pin PIO0_21 (this is the default). A LOW-going pulse as short as 50 ns executes the reset and thereby wakes up the part to its active state. The $\overline{\text{RESET}}$ pin is not functional in Deep power-down mode and must be pulled HIGH externally while the part is in Deep power-down mode.

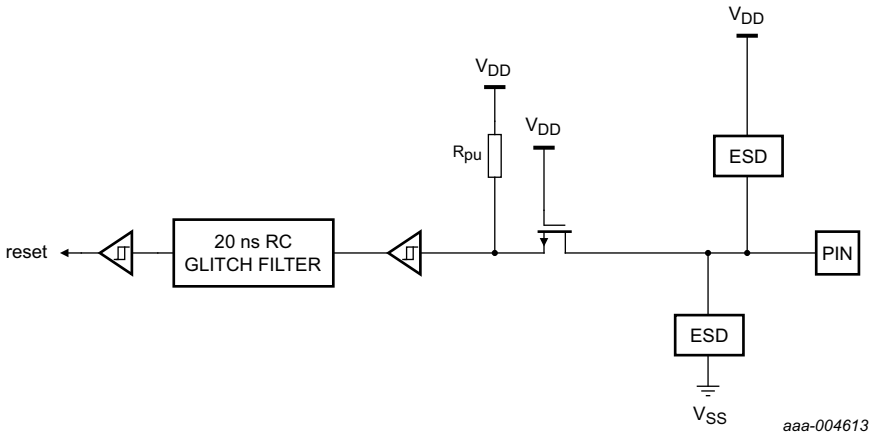


Fig 16. $\overline{\text{RESET}}$ pin configuration

8.41.2 Brownout detection

The LPC15xx includes brown-out detection (BOD) with two levels for monitoring the voltage on the V_{DD} pin. If this voltage falls below one of two selected levels, the BOD asserts an interrupt signal to the NVIC. This signal can be enabled for interrupt in the Interrupt Enable Register in the NVIC to cause a CPU interrupt. Alternatively, software can monitor the signal by reading a dedicated status register. Two threshold levels can be selected to cause a forced reset of the chip.

8.41.3 Code security (Code Read Protection - CRP)

CRP provides different levels of security in the system so that access to the on-chip flash and use of the Serial Wire Debugger (SWD) and In-System Programming (ISP) can be restricted. Programming a specific pattern into a dedicated flash location invokes CRP. IAP commands are not affected by the CRP.

In addition, ISP entry the external pins can be disabled without enabling CRP. For details, see the LPC15xx *user manual*.

There are three levels of Code Read Protection:

1. CRP1 disables access to the chip via the SWD and allows partial flash update (excluding flash sector 0) using a limited set of the ISP commands. This mode is useful when CRP is required and flash field updates are needed but all sectors cannot be erased.
2. CRP2 disables access to the chip via the SWD and only allows full flash erase and update using a reduced set of the ISP commands.
3. Running an application with level CRP3 selected, fully disables any access to the chip via the SWD pins and the ISP. This mode effectively disables ISP override using ISP pin as well. If necessary, the application must provide a flash update mechanism using IAP calls or using a call to the reinvoke ISP command to enable flash update via the USART.

CAUTION

If level three Code Read Protection (CRP3) is selected, no future factory testing can be performed on the device.

In addition to the three CRP levels, sampling of the ISP pins for valid user code can be disabled. For details, see the LPC15xx *user manual*.

The internal power dissipation is the product of I_{DD} and V_{DD}. The I/O power dissipation of the I/O pins is often small and many times can be negligible. However it can be significant in some applications.

11. Static characteristics

Table 11. Static characteristics

T_{amb} = −40 °C to +105 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
V_{DD}	supply voltage (core and external rail)	[2]	2.4	3.3	V_{DDA}	V
V_{DDA}	analog supply voltage		2.4	3.3	3.6	V
V_{ref}	reference voltage	on pin VREFP_DAC_VDDCMP	2.4	-	V_{DDA}	V
		on pin VREFP_ADC	-	-	V_{DDA}	V
V_{BAT}	battery supply voltage		2.4	3.3	3.6	V
I_{DD}	supply current	Active mode; code `while(1){}` executed from flash;				
		system clock = 12 MHz; default mode; V_{DD} = 3.3 V [3][4][5][7][8]	-	4.3	-	mA
		system clock = 12 MHz; low-current mode; V_{DD} = 3.3 V [3][4][5][7][8]	-	2.7	-	mA
		system clock = 72 MHz; default mode; V_{DD} = 3.3 V [3][4][7][8][10]	-	19.3	-	mA
		system clock = 72 MHz; low-current mode; V_{DD} = 3.3 V [3][4][7][8][10]	-	18	-	mA
		Sleep mode;				
		system clock = 12 MHz; default mode; V_{DD} = 3.3 V [3][4][5][7][8]	-	2.1	-	mA
		system clock = 12 MHz; low-current mode; V_{DD} = 3.3 V [3][4][5][7][8]	-	1.5	-	mA
		system clock = 72 MHz; default mode; V_{DD} = 3.3 V [3][4][10][7][8]	-	8.0	-	mA
		system clock = 72 MHz; low-current mode; V_{DD} = 3.3 V [3][4][10][7][8]	-	7.3	-	mA
I_{DD}	supply current	Deep-sleep mode; V_{DD} = 3.3 V; [3][4][11]	-			
		T_{amb} = 25 °C		310	380	µA
		T_{amb} = 105 °C	-	-	620	µA
I_{DD}	supply current	Power-down mode; V_{DD} = 3.3 V [3][4][11]	-			
		T_{amb} = 25 °C		3.8	15	µA
		T_{amb} = 105 °C	-	-	163	µA

Table 11. Static characteristics *…continued*
T_{amb} = −40 °C to +105 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
I_{DD}	supply current	Deep power-down mode; V_{DD} = 3.3 V; VBAT = 0 or VBAT = 3.0 V [3][12][13]				
		RTC oscillator running				
		T_{amb} = 25 °C	-	1.1	1.3[14]	µA
		T_{amb} = 105 °C	-	-	15	µA
		RTC oscillator input grounded; T_{amb} = 25 °C [3][12]	-	560	-	nA
I_{BAT}	battery supply current	Deep power-down mode; V_{DD} = V_{DDA} = 3.3 V; VBAT = 3.0 V [13]		0	-	nA
		V_{DD} and V_{DDA} tied to ground; VBAT = 3.0 V [13]		1	-	µA
Standard port pins configured as digital pins, $\overline{\text{RESET}}$; see Figure 17						
I_{IL}	LOW-level input current	V_I = 0 V; on-chip pull-up resistor disabled	-	0.5	10[14]	nA
I_{IH}	HIGH-level input current	V_I = V_{DD}; on-chip pull-down resistor disabled	-	0.5	10[14]	nA
I_{OZ}	OFF-state output current	V_O = 0 V; V_O = V_{DD}; on-chip pull-up/down resistors disabled	-	0.5	10[14]	nA
V_I	input voltage	$V_{DD} \geq$ 2.4 V; 5 V tolerant pins except PIO0_12 [16] [18]	0	-	5	V
		$V_{DD} \geq$ 2.4 V; on 3 V tolerant pin PIO0_12	0	-	V_{DDA}	
		V_{DD} = 0 V	0	-	3.6	V
V_O	output voltage	output active	0	-	V_{DD}	V
V_{IH}	HIGH-level input voltage		$0.7V_{DD}$	-	-	V
V_{IL}	LOW-level input voltage		-	-	$0.3V_{DD}$	V
V_{hys}	hysteresis voltage	2.4 V <= V_{DD} < 3.0 V	0.30	-	-	V
		3.0 V <= V_{DD} <= 3.6 V	0.35	-	-	V
V_{OH}	HIGH-level output voltage	I_{OH} = 4 mA	V_{DD} − 0.4	-	-	V
V_{OL}	LOW-level output voltage	I_{OL} = 4 mA	-	-	0.4	V
I_{OH}	HIGH-level output current	V_{OH} = V_{DD} − 0.4 V	4	-	-	mA
I_{OL}	LOW-level output current	V_{OL} = 0.4 V	4	-	-	mA
I_{OHS}	HIGH-level short-circuit output current	V_{OH} = 0 V [19]	-	-	-45	mA
I_{OLS}	LOW-level short-circuit output current	V_{OL} = V_{DD} [19]	-	-	50	mA
I_{pd}	pull-down current	V_I = 5 V	10	50	150	µA
I_{pu}	pull-up current	V_I = 0 V;	−10	−50	−85	µA
		V_{DD} < V_I < 5 V	0	0	0	µA

[5] IRC enabled; system oscillator disabled; system PLL disabled.

[6] System oscillator enabled; IRC disabled; system PLL disabled.

[7] BOD disabled.

[8] All peripherals disabled in the SYSAHBCLKCTRL0/1 registers. Peripheral clocks to USART, CLKOUT, and IOCON disabled in system configuration block.

[9] IRC enabled; system oscillator disabled; system PLL enabled.

[10] IRC disabled; system oscillator enabled; system PLL enabled.

[11] All oscillators and analog blocks turned off: Use API power_mode_configure() with mode parameter set to DEEP_SLEEP or POWER_DOWN and peripheral parameter set to 0xFF.

[12] WAKEUP pin pulled HIGH externally.

[13] RTC running or not running.

[14] Characterized on samples. Not tested in production.

[15] Low-current mode PWR_LOW_CURRENT selected when running the set_power routine in the power profiles.

[16] Including voltage on outputs in tri-state mode.

[17] V_{DD} supply voltage must be present.

[18] Tri-state outputs go into tri-state mode in Deep power-down mode.

[19] Allowed as long as the current limit does not exceed the maximum current allowed by the device.

[20] Pull-up and pull-down currents are measured across the weak internal pull-up/pull-down resistors. See Figure 17.

[21] To V_{SS}.

[22] The parameter values specified are simulated and absolute values.

[23] The input voltage of the RTC oscillator is limited as follows: $V_{i(rtcx)}$, $V_{o(rtcx)}$ < max(VBAT, V_{DD}).

[24] Including bonding pad capacitance.

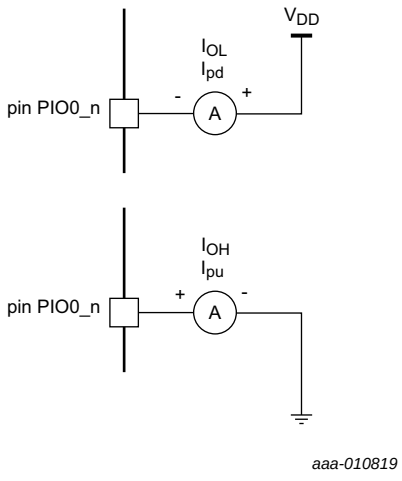
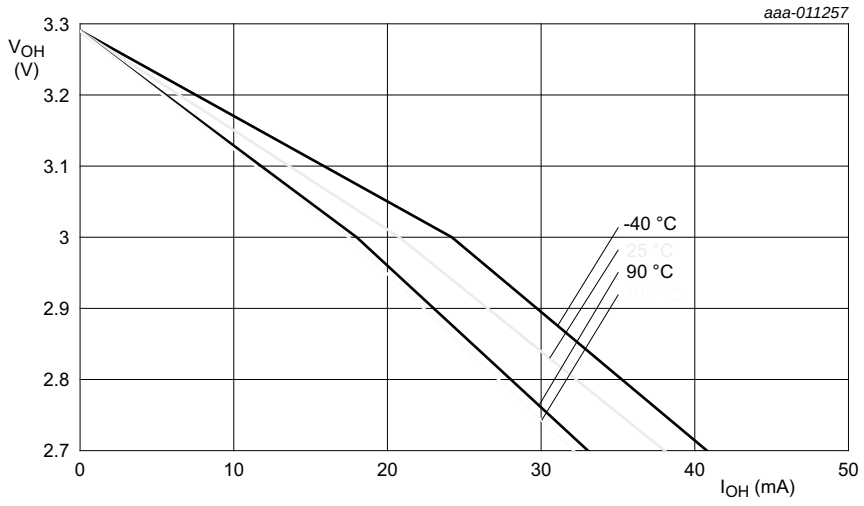


Fig 17. Pin input/output current measurement

Table 12. Power consumption for individual analog and digital blocks *…continued*

Peripheral	Typical supply current in mA			Notes
	n/a	12 MHz	72 MHz	
USART0	-	0.02	0.15	-
USART1	-	0.02	0.16	-
USART2	-	0.02	0.15	-
C_CAN	-	0.50	3.00	
USB	-	0.10	0.50	
Comparator ACMP0/1/2/3	-	0.01	0.03	-
ADC0	-	0.05	0.33	-
ADC1	-	0.04	0.33	-
temperature sensor	-	0.03	0.03	
internal voltage reference/band gap	-	0.03	0.04	
DAC	-	0.02	0.09	-
DMA	-	0.36	1.5	
CRC	-	0.01	0.08	-

11.4 Electrical pin characteristics



Conditions: V_{DD} = 3.3 V; on pin PIO0_24.

Fig 27. High-drive output: Typical HIGH-level output voltage V_{OH} versus HIGH-level output current I_{OH}

Table 19. Dynamic characteristic: I²C-bus pins[1]

T_{amb} = −40 °C to +105 °C; values guaranteed by design.[2]

Symbol	Parameter	Conditions	Min	Max	Unit
$t_{SU;DAT}$	data set-up time [9][10]	Standard-mode	250	-	ns
		Fast-mode	100	-	ns
		Fast-mode Plus; on pins PIO0_22 and PIO0_23	50	-	ns

[1] See the I²C-bus specification *UM10204* for details.

[2] Parameters are valid over operating temperature range unless otherwise specified.

[3] $t_{HD;DAT}$ is the data hold time that is measured from the falling edge of SCL; applies to data in transmission and the acknowledge.

[4] A device must internally provide a hold time of at least 300 ns for the SDA signal (with respect to the V_{IH}(min) of the SCL signal) to bridge the undefined region of the falling edge of SCL.

[5] C_b = total capacitance of one bus line in pF.

[6] The maximum t_f for the SDA and SCL bus lines is specified at 300 ns. The maximum fall time for the SDA output stage t_f is specified at 250 ns. This allows series protection resistors to be connected in between the SDA and the SCL pins and the SDA/SCL bus lines without exceeding the maximum specified t_f.

[7] In Fast-mode Plus, fall time is specified the same for both output stage and bus timing. If series resistors are used, designers should allow for this when considering bus timing.

[8] The maximum $t_{HD;DAT}$ could be 3.45 µs and 0.9 µs for Standard-mode and Fast-mode but must be less than the maximum of $t_{VD;DAT}$ or $t_{VD;ACK}$ by a transition time (see *UM10204*). This maximum must only be met if the device does not stretch the LOW period (t_{LOW}) of the SCL signal. If the clock stretches the SCL, the data must be valid by the set-up time before it releases the clock.

[9] $t_{SU;DAT}$ is the data set-up time that is measured with respect to the rising edge of SCL; applies to data in transmission and the acknowledge.

[10] A Fast-mode I²C-bus device can be used in a Standard-mode I²C-bus system but the requirement $t_{SU;DAT}$ = 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line $t_{r(max)} + t_{SU;DAT}$ = 1000 + 250 = 1250 ns (according to the Standard-mode I²C-bus specification) before the SCL line is released. Also the acknowledge timing must meet this set-up time.

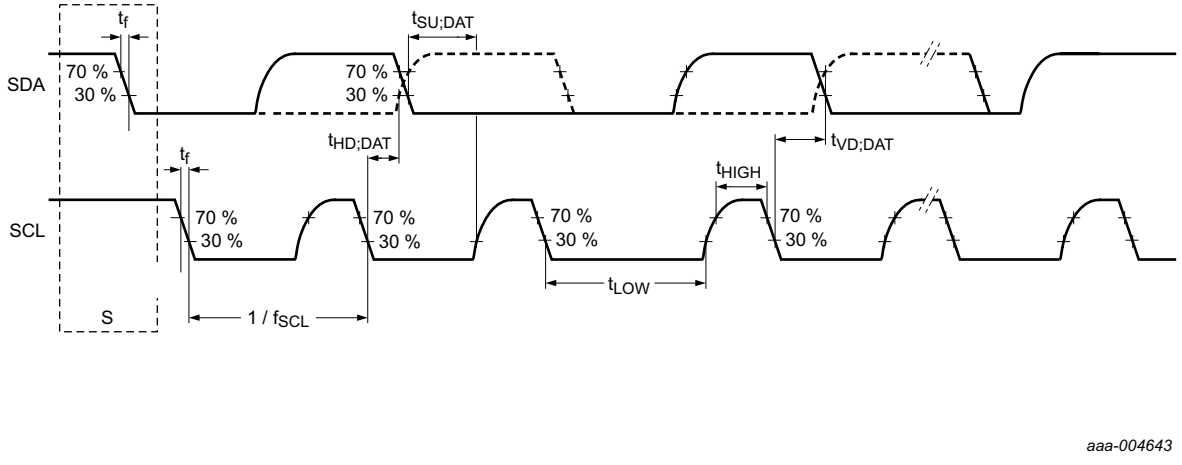


Fig 35. I²C-bus pins clock timing

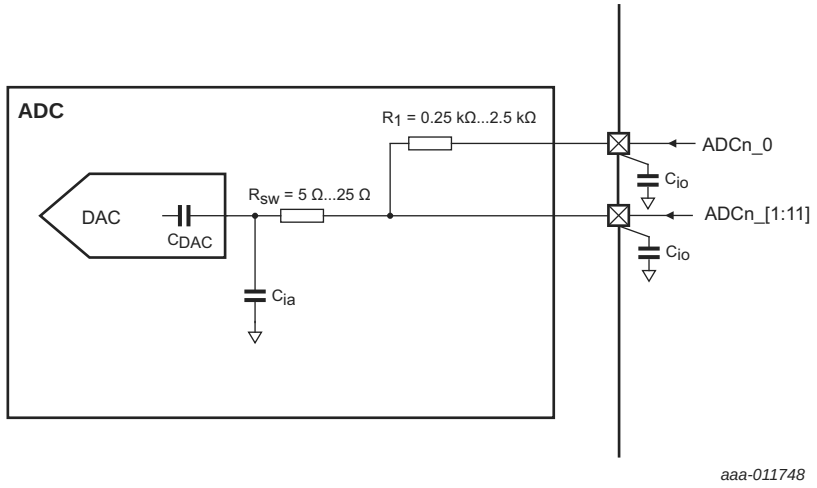
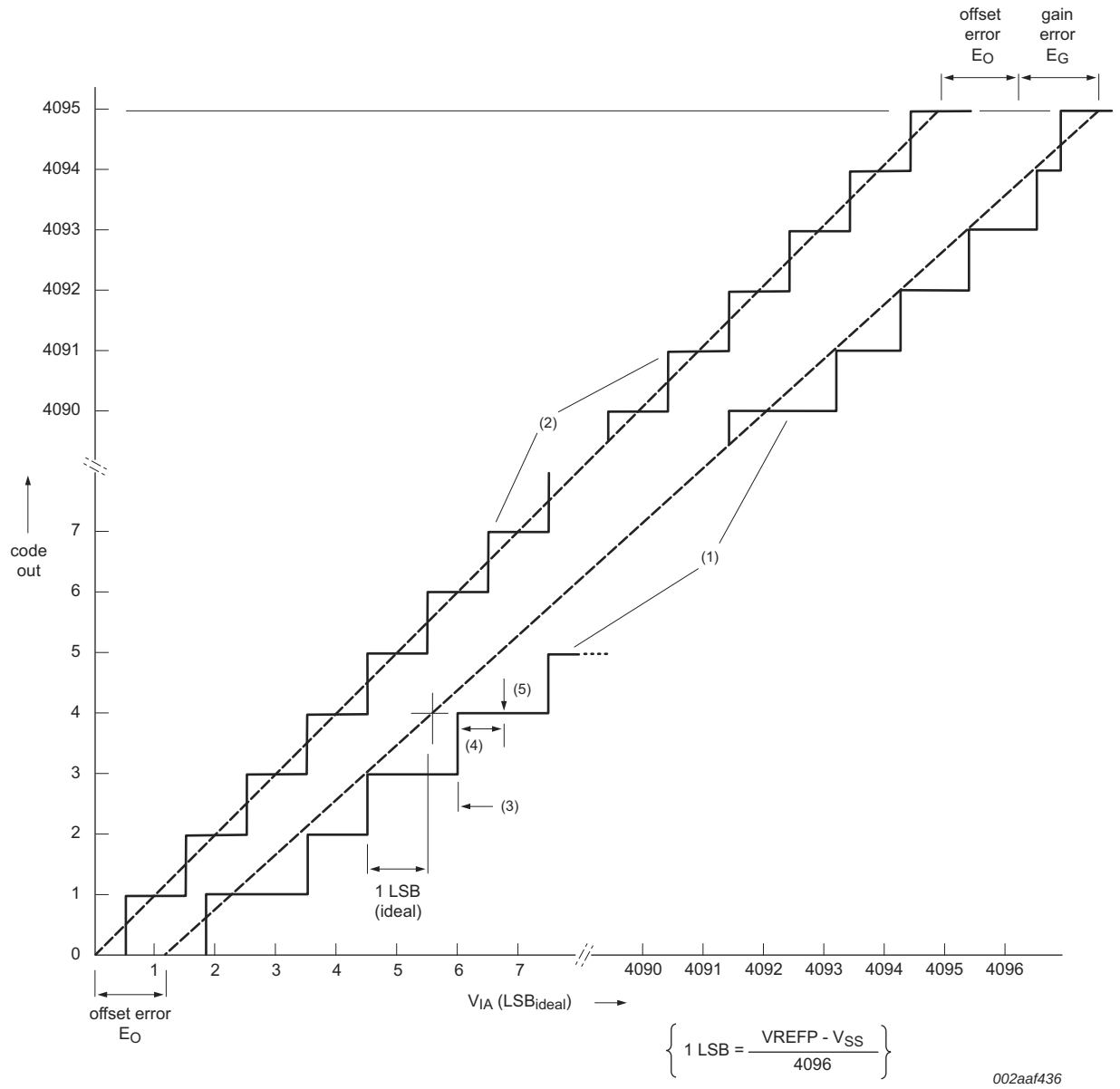


Fig 39. ADC input impedance



(1) Example of an actual transfer curve.

(2) The ideal transfer curve.

(3) Differential linearity error (E_D).

(4) Integral non-linearity ($E_{L(adj)}$).

(5) Center of a step of the actual transfer curve.

Fig 40. 12-bit ADC characteristics

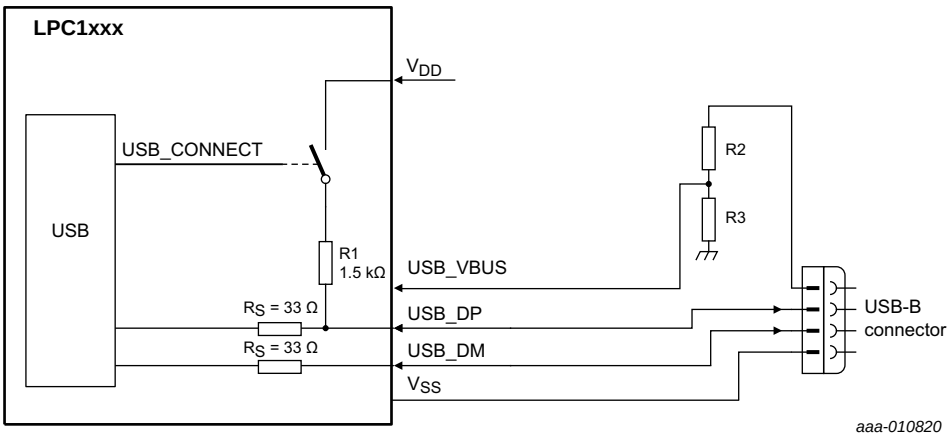


Fig 44. USB interface on a self-powered device where USB_VBUS = 5 V

For a bus-powered device, the VBUS signal does not need to be connected to the USB_VBUS pin (see Figure 45). The USB_CONNECT function can additionally be enabled internally by setting the DCON bit in the DEVCMDSTAT register to prevent the USB from timing out when there is a significant delay between power-up and handling USB traffic. External circuitry is not required for the USB_CONNECT functionality.

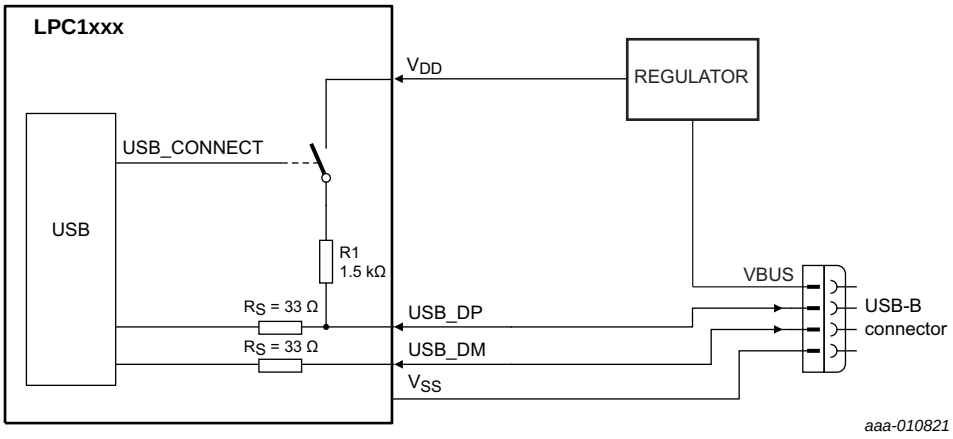


Fig 45. USB interface on a bus-powered device

Remark: When a bus-powered circuit as shown in Figure 45 is used or, for a self-powered device, when the VBUS pin is not connected, configure the PIO0_3/USB_VBUS pin for GPIO (PIO0_3) in the IOCON block. This ties the VBUS signal HIGH internally.

14.2.1 USB Low-speed operation

The USB device controller can be used in low-speed mode supporting 1.5 Mbit/s data exchange with a USB host controller.

Remark: To operate in low-speed mode, change the board connections as follows:

1. Connect USB_DP to the D- pin of the connector.
2. Connect USB_DM to the D+ pin of the connector.

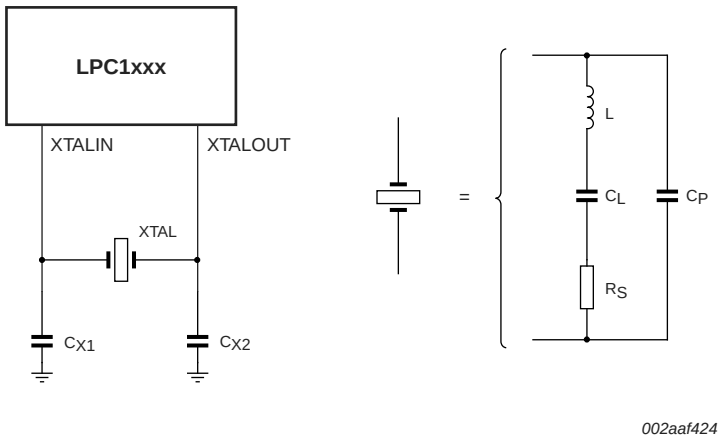


Fig 47. Oscillator modes and models: oscillation mode of operation and external crystal model used for C_{X1}/C_{X2} evaluation

Table 32. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters) low frequency mode

Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
1 MHz to 5 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 300 Ω	39 pF, 39 pF
	30 pF	< 300 Ω	57 pF, 57 pF
5 MHz to 10 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 200 Ω	39 pF, 39 pF
	30 pF	< 100 Ω	57 pF, 57 pF
10 MHz to 15 MHz	10 pF	< 160 Ω	18 pF, 18 pF
	20 pF	< 60 Ω	39 pF, 39 pF
15 MHz to 20 MHz	10 pF	< 80 Ω	18 pF, 18 pF

Table 33. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters) high frequency mode

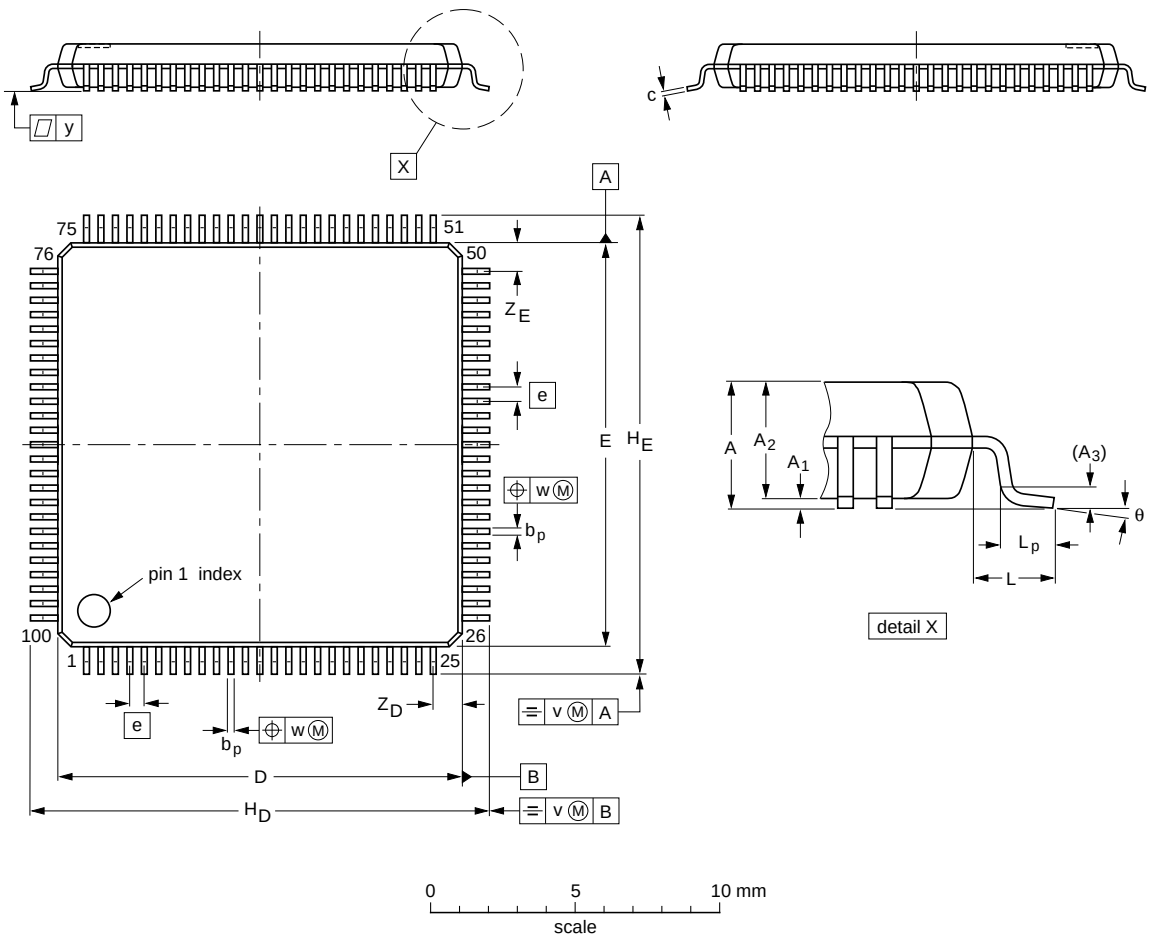
Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
15 MHz to 20 MHz	10 pF	< 180 Ω	18 pF, 18 pF
	20 pF	< 100 Ω	39 pF, 39 pF
20 MHz to 25 MHz	10 pF	< 160 Ω	18 pF, 18 pF
	20 pF	< 80 Ω	39 pF, 39 pF

14.4 XTAL Printed-Circuit Board (PCB) layout guidelines

The crystal should be connected on the PCB as close as possible to the oscillator input and output pins of the chip. Take care that the load capacitors C_{x1}, C_{x2}, and C_{x3} in case of third overtone crystal usage have a common ground plane. The external components must also be connected to the ground plane. Loops must be made as small as possible in

order to keep the noise coupled in via the PCB as small as possible. Also parasitics should stay as small as possible. Smaller values of C_{x1} and C_{x2} should be chosen according to the increase in parasitics of the PCB layout.

LQFP100: plastic low profile quad flat package; 100 leads; body 14 x 14 x 1.4 mm **SOT407-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	1.6	0.15 0.05	1.45 1.35	0.25	0.27 0.17	0.20 0.09	14.1 13.9	14.1 13.9	0.5	16.25 15.75	16.25 15.75	1	0.75 0.45	0.2	0.08	0.08	1.15 0.85	1.15 0.85	7^o 0^o

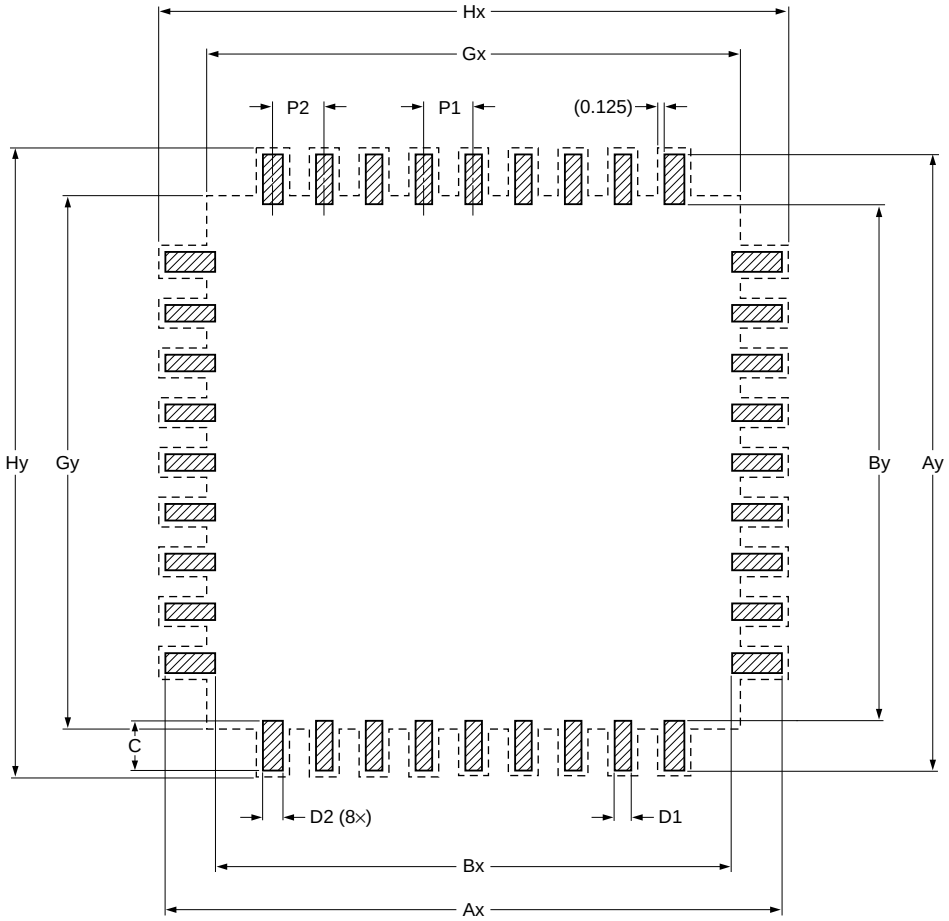
Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT407-1	136E20	MS-026				~~00-02-01~~ 03-02-20

Fig 52. Package outline LQFP100 (SOT407-1)

Footprint information for reflow soldering of LQFP64 package **SOT314-2**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	13.300	13.300	10.300	10.300	1.500	0.280	0.400	10.500	10.500	13.550	13.550

sot314-2_fr

Fig 54. Reflow soldering for the LQFP64 package

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

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